

13 second circuitized card are electrically and physically connected through a ball
14 grid array.

Cancel claims 6, 13, 14, 24 and 25 .

1 20. (4th amendment) A package for containing electronic components, the
2 package comprising:
3 a first circuitized card having a top and bottom surface;
4 a second circuitized card having a top and bottom surface;
5 an interposer having an opening, a top surface, and a bottom surface, the
6 interposer being electrically connected to the first circuitized card and the second
7 circuitized card through a first and second set of connections, the first set of
8 connections being interposed between the bottom surface of the first circuitized
9 card and the top surface of the interposer, the second set of connections being
10 interposed between the bottom surface of the interposer and the top surface of
11 the second circuitized card, wherein (a) the bottom surface of the second
12 circuitized card has a third set of connections for attaching the second circuitized
13 card to a system card, (b) the opening in the interposer, the bottom surface of
14 the first circuitized card, and the top surface of the second circuitized card form a
15 cavity for containing at least one electronic component, (c) the interposer, first
16 circuitized card, and second circuitized card are circuitized multi-layer organic
17 laminate cards, and (d) each set of connections of the first, second and third sets
18 of connections is a ball grid array.

1 35. (amended) The package of claim 20 further comprising a third circuitized
2 card and a second interposer having a second opening, wherein the third
3 circuitized card, the second circuitized card, and the second opening in
4 the second interposer define a second cavity for containing at least one
5 electronic component, wherein the third circuitized card is electrically

6 connected to the second interposer through a fourth set of connections,
 7 and wherein the second interposer is electrically connected to the second
 8 circuitized card through a fifth set of connections.

Add the following new claim:

1 54. (new) A package for containing electronic components, the package
 2 comprising:
 3 a first circuitized card having a top and bottom surface;
 4 a second circuitized card having a top and bottom surface;
 5 an interposer having an opening, a top surface, and a bottom surface, the
 6 interposer being electrically connected to the first circuitized card and the second
 7 circuitized card through a first and second set of connections, the first set of
 8 connections being interposed between the bottom surface of the first circuitized
 9 card and the top surface of the interposer, the second set of connections being
 10 interposed between the bottom surface of the interposer and the top surface of
 11 the second circuitized card, wherein (a) the bottom surface of the second
 12 circuitized card has a third set of connections for attaching the second circuitized
 13 card to a system card, (b) the opening in the interposer, the bottom surface of
 14 the first circuitized card, and the top surface of the second circuitized card form a
 15 cavity for containing at least one electronic component, (c) the interposer, first
 16 circuitized card, and second circuitized card are circuitized multi-layer organic
 17 laminate cards, and (d) said interposer has at least one electronic component on
 18 its surface.

Remarks

The above amendment is submitted in response to the office action dated
 August 28, 2002.